

12-06-01

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Docket No.: M-9433 US

November 15, 2001

Box Patent Application
Commissioner For Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventor: Adrian E. Ong
Title: Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices

X Return Receipt Postcard
X This Transmittal Letter (in duplicate)
14 pages Specification (not including claims)
7 pages Claims
1 page Abstract
9 Sheets of Drawings (Figs. 1, 2, 3, 4, 5, 6, 7, 8, and 9)
2 pages Declaration For Patent Application and Power of Attorney
1 page NonPublication Request
1 page Information Disclosure Statement
1 page PTO Form 1449 citing 2 references
☒ Copies of 2 Cited References submitted

☒ Applicant(s) assert(s) entitlement to small entity status for the attached patent application**CLAIMS AS FILED (fees computed under 37 CFR §1.9(f))**

For	Number Filed		Number Extra		Rate		Basic Fee
Total Claims	38	-20 =	18	x	\$ 9.00	=	\$ 162.00
Independent Claims	7	-3 =	4	x	\$42.00	=	\$ 168.00
<input type="checkbox"/> Fee of _____ for the first filing of one or more multiple dependent claims per application							\$
<input type="checkbox"/> Fee for Request for Extension of Time							\$

Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 700.00
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:
EL 707 911 005 US

Respectfully submitted,


Peter G. Mikhail
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10/003375
11/15/01

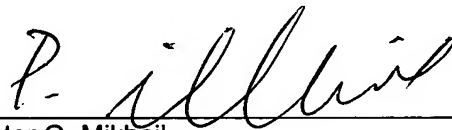
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MODIFIED PTO/SB/35 (11-00)

REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)	Inventor	Adrian E. Ong
	Title	Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices
	Atty Docket Number	M-9433 US

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

November 15, 2001
Date


Peter G. Mikhail
Reg. No.: 46,930

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**